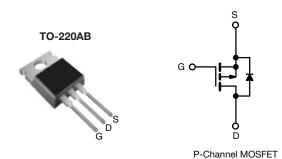
Vishay Siliconix



Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V)	-6	0
$R_{DS(on)}(\Omega)$	V _{GS} = -10 V	0.14
Q _g max. (nC)	3	4
Q _{gs} (nC)	9.	9
Q _{gd} (nC)	1	6
Configuration	Sin	gle

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9Z34PbF
Lead (Pb)-free and halogen-free	IRF9Z34PbF-BE3

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-60	V		
Gate-source voltage			V _{GS}	± 20	v	
Continuous drain current	V_{GS} at 10 V $T_C = 25 \degree C$ $T_C = 100 \degree C$ I_D		-18			
Continuous drain current	V _{GS} at 10 V	T _C = 100 °C	I _D	-13	Α	
Pulsed drain current ^a I _{DM}		-72				
Linear derating factor				0.59	W/°C	
Single pulse avalanche energy b			E _{AS}	370	mJ	
Repetitive avalanche current a			I _{AR}	-18	Α	
Repetitive avalanche energy ^a			E _{AR}	8.8	mJ	
Maximum power dissipation $T_C = 25 ^{\circ}C$		P _D	88	W		
Peak diode recovery dV/dt ^c		dV/dt	-4.5	V/ns		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^d For 10 s 300		300				
Mounting town	10	10	lbf ⋅ in			
Mounting torque	6-32 or M3 screw			1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = -25 V, starting T_J = 25 °C, L = 1.3 mH, R_q = 25 Ω , I_{AS} = -18 A (see fig. 12)
- c. $I_{SD} \le -18$ A, $dI/dt \le 170$ A/ μ s, $V_{DD} \le V_{DS}$, $T_{J} \le 175$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	1.7	

SPECIFICATIONS (T _J = 25 °C, t	ınless otherw	ise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		*					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-60	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = -1 mA		-	-0.060	=	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{C}$	V _{DS} = V _{GS} , I _D = 250 μA		-	-4.0	V
Gate-source leakage	I _{GSS}	V _G	V _{GS} = ± 20 V		-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V		-	_	-100	- μΑ
		V _{DS} = -48 V, V	V _{DS} = -48 V, V _{GS} = 0 V, T _J = 150 °C		-	-500	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = -10 V	I _D = -11 A ^b	-	-	0.14	Ω
Forward transconductance	9 _{fs}	V _{DS} = -25 V, I _D = -11 A ^b		5.9	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$ f = 1.0 MHz, see fig. 5		-	1100	_	pF
Output capacitance	C _{oss}			-	620	-	
Reverse transfer capacitance	C _{rss}			-	100	-	
Total gate charge	Qg		$I_D = -1.8 \text{ A},$ $V_{DS} = -48 \text{ V},$ see fig. 6 and 13 b	-	-	34	nC
Gate-source charge	Q_{gs}	V _{GS} = -10 V		-	-	9.9	
Gate-drain charge	Q_{gd}			-	-	16	
Turn-on delay time	t _{d(on)}			-	18	-	1
Rise time	t _r	V_{DD} = -30 V, I_{D} = -18 A, R_{g} = 12 Ω , R_{D} = 1.5 Ω , see fig. 10 ^b		-	120	-	ns
Turn-off delay time	t _{d(off)}			-	20	-	
Fall time	t _f			-	58	-	
Gate input resistance	L _D		Between lead, 6 mm (0.25") from		4.5	-	ьЦ
Internal drain inductance	L _S	package and center of die contact		-	7.5	-	- nH
Internal source inductance	R_g	f = 1 MHz, open drain		0.7	-	3.9	Ω
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	Is	showing the	MOSFET symbol showing the		-	-18	A
Pulsed diode forward current ^a	I _{SM}	integral reverse p -n junction diode		-	-	-72	
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, \ I_S = -18 \text{A}, \ V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	-6.3	V
Body diode reverse recovery time	t _{rr}	T 25 °C 1	19 A dl/dt = 100 A/a h		100	200	ns
Body diode reverse recovery charge	Q _{rr}	1J = 20 C, I _F = -	18 A, dl/dt = 100 A/µs b	-	0.28	0.52	μC
Forward turn-on time	t _{on}	Intrinsic turn	n-on is do	minated b	by L _S and L _D)		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

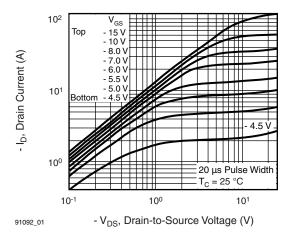


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

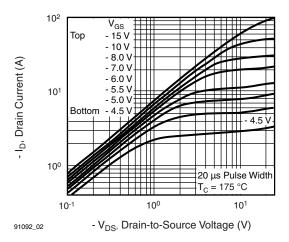


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

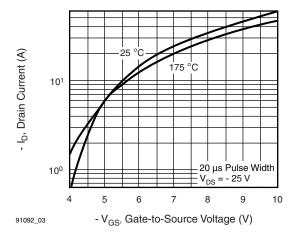


Fig. 3 - Typical Transfer Characteristics

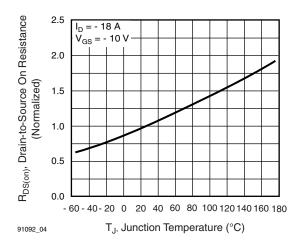


Fig. 4 - Normalized On-Resistance vs. Temperature

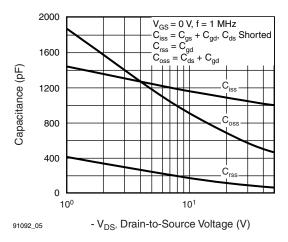


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

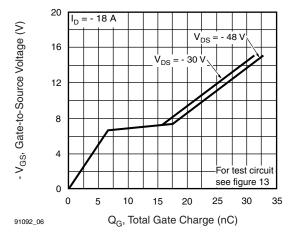


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



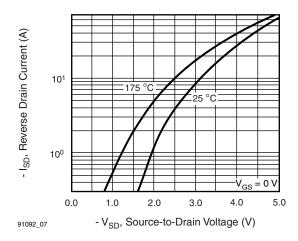


Fig. 7 - Typical Source-Drain Diode Forward Voltage

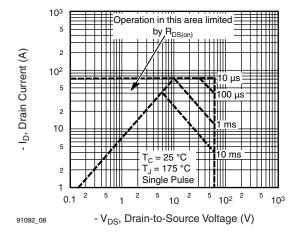


Fig. 8 - Maximum Safe Operating Area

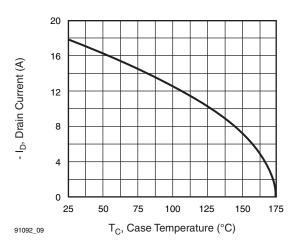


Fig. 9 - Maximum Drain Current vs. Case Temperature

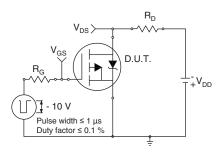


Fig. 10a - Switching Time Test Circuit

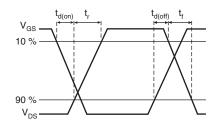


Fig. 10b - Switching Time Waveforms

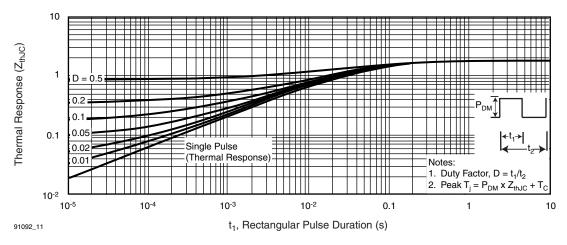


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



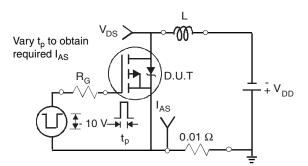


Fig. 12a - Unclamped Inductive Test Circuit

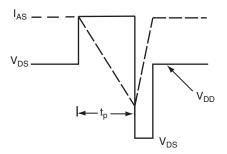


Fig. 12b - Unclamped Inductive Waveforms

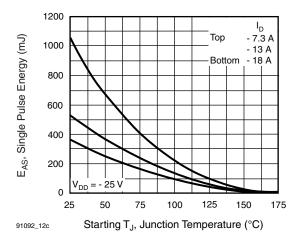


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

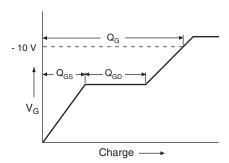


Fig. 13a - Basic Gate Charge Waveform

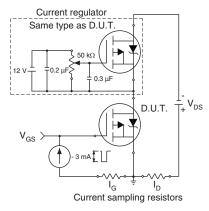
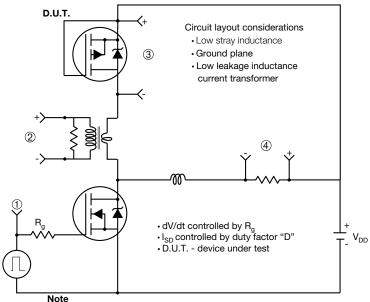


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

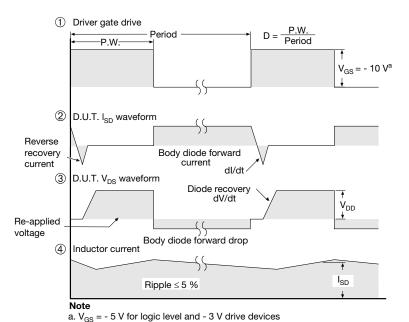
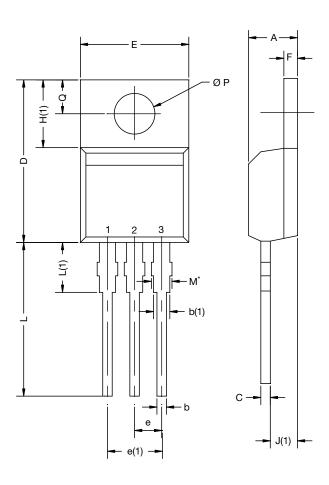


Fig. 14 - For P-Channel

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TO-220-1



DIM.	MILLIM	METERS	INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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